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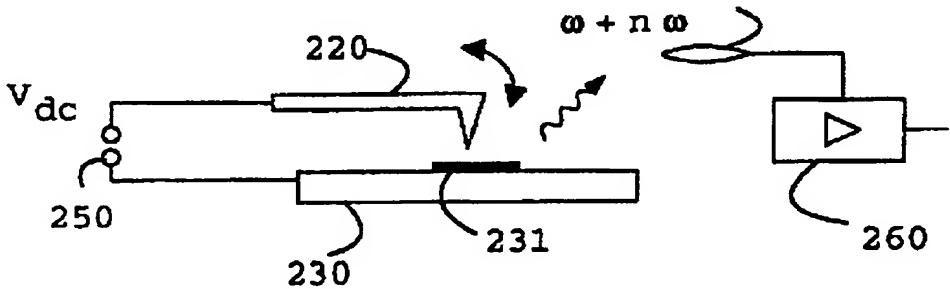
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(71) Applicant (for all designated States except US): INTERNATIONAL BUSINESS MACHINES CORP. [US/US]; Old Orchard Road, Armonk, NY 10504 (US).	Published <i>With international search report.</i>
(72) Inventors; and	
(75) Inventors/Applicants (for US only): BOURGOIN, Jean-Philippe, Marie [FR/FR]; 5, rue des Arcades, F-78180 Montigny-le-Bx (FR). JOHNSON, Matthew, Bruce [CA/CH]; Fachstrasse 38, CH-8942 Oberrieden (CH). MICHEL, Bruno [CH/CH]; Obstgartenweg 13, CH-8136 Gatlikon (CH).	
(74) Agent: BARTH, Carl, Otto; International Business Machines Corporation, Säumerstrasse 4, CH-8803 Rüschlikon (CH).	

(54) Title: CANTILEVER DEFLECTION SENSOR AND USE THEREOF

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## (57) Abstract

A new method and an apparatus for measuring the deflection of or the force exerted upon a cantilever-type micromechanical element is presented which is based on detecting radiation emitted from the gap between the cantilever (220) and a second surface (230, 231). The radiation, while occurring spontaneously at high frequencies when appropriately biasing the cantilever and the second surface by a voltage, can be enlarged by using external energy sources. The new method and apparatus are also applied to surface investigation, particularly to dopant profiling.

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## DESCRIPTION

**Cantilever deflection sensor and use thereof**

5

This invention relates generally to means for measuring the forces and/or deflections of cantilever type elements, as encountered for example in the field of Atomic Force Microscopy (AFM). The invention further relates to a 10 method and apparatus for determining material properties. In particular, it relates to a dopant profiler based on a scanning probe microscope involving the generation and detection of higher harmonics of an applied electromagnetic field.

15

## BACKGROUND OF THE INVENTION

The Atomic Force Microscope as first known from the United States patent 20 US-A-4 724 318 and further described by G. Binnig, C.F. Quate and Ch. Gerber in Phys. Rev. Letters, Vol.56, No.9, March 1986, pp.930-933, employs a sharply pointed tip attached to a spring-like cantilever beam to scan the profile of a surface to be investigated. At the distances involved, minute forces occur between the atoms at the apex of the tip and those at 25 the surface, resulting in a tiny deflection of the cantilever. In US-A-4 724 318, this deflection is measured by means of a tunnelling microscope, i.e., an electrically conductive tunnel tip is placed within tunnelling distance from the back of the cantilever beam made also conductive, and the variations of the tunnelling current are used to 30 determine the deflection. With known characteristics of the cantilever beam, the forces occurring between the AFM tip and the surface under investigation can be determined.

- 1 The forces occurring between a pointed tip and a surface are usually described as van-der-Waals, covalent, ionic, or repulsive core interaction forces.
- 5 An important aspect of AFM is to accurately determine the deflection of the cantilever. One group of these deflection measuring methods is based on coupling the cantilever to another distance sensitive microscope. A combination of the cantilever with a scanning tunneling microscope is described, for example, in the above mentioned patent US-A-4 724 318.
- 10 Another approach using an evanescent wave coupling sensor, also known as scanning near-field optical microscope (SNOM) or scanning tunneling optical microscope (STOM), is described by Diaspro and Aguilar in: Ultramicroscopy 42-44 (1992), pp. 1668-1670.
- 15 Another group of detecting methods is based on the well known piezoelectric or piezoresistive effect. An example is described in: M. Tortenese et al., Appl. Phys. Lett. 62(8), 1993, pp.834-836. These methods provide detection schemes in which the deflection detector is integrated in the cantilever.
- 20 Yet another feasible way of detecting the displacement of the cantilever relies on capacitance sensing and is known, for example, from Joyce et al., Rev. Sci. Instr. 62(1991), p. 710, and Göddenhenrich et al., J. Vac. Sci. Technol. A8(1990), p. 383. and the European patent application EP-A-0 290 648.
- 25 By this application as well as from United States patent US-A-4 851 671 methods are known use the changes in the resonance frequencies of the flexible element and higher harmonics thereof to measure its bending. The frequencies are detected either by a quartz oscillator or by a capacitance additionally attached to the cantilever.

1      The displacement of the flexible element can also be measured by applying  
optical methods, such as beam deflection or Interferometry. The beam  
deflection method makes use of the length of the lever. Usually, a light  
5      beam, preferably produced by a laser diode or guided through an optical  
fiber, is directed onto the lever. A small deflection of the lever causes a  
reasonable change in the reflecting angle and, therefore, results in a  
deflection of the reflected light beam that is measured with bicell or other  
suitable photo detectors. The beam deflection method is simple and  
10     reliable. It is described, for example, by Myer and Amer in Appl. Phys. Lett.  
53 (1988), pp.1045-1047. Interferometric methods are described, for  
example, by Martin et al., J. Appl. Phys. 61(1987), p.4723, by Sarid et al.,  
Opt.Lett. 12(1988), p.1057, and by Oshio et al., Ultramicroscopy 42-44(1992),  
pp.310-314. As the sensitivity of the SPM can be increased by building  
15     cantilevers with ever higher resonance frequencies while trying to maintain  
the Q factor, a tendency towards smaller cantilevers can be observed. For  
these cantilevers the above optical methods are prone to failure due to a  
diminished reflectivity and problems which arise from the limited focus size  
of a laser beam.

20     Present day very large scale integrated (VLSI) circuit technology demands  
an accurate knowledge of the spatial extent, density, or distribution in all  
three dimensions of the active components (dopants) which are introduced  
into a base or host material. The most common devices produced by VLSI  
25     are either bipolar or metal oxide semiconductor field effect (MOSFET)  
transistors, diodes or capacitors. The characteristic length scale - at  
present at about 0.5 microns - will shrink in the future to 350 nm and even to  
100 nm. The concentration of dopants, for example arsenic, boron, or  
phosphorous, in an active region of a semiconducting device ranges  
30     typically from  $10^{15}/\text{cm}^3$  to  $10^{20}/\text{cm}^3$ . It will become necessary to control  
the variation, or profile, of dopants with a lateral resolution of 10 nm and a  
vertical resolution of 2 - 3 nm to accomplish predictability in device behavior  
and control of the manufacturing process. However, currently known dopant

1 profilers are unable to provide this high precision, at least in all three  
dimensions.

5 Known approaches to dopant profiling include junction staining as  
described by S.T. Ahn and W.A. Tiller in the J. Electrochem. Soc. 135  
(1988), p. 2370, dopant density selective etching with Transmission Electron  
microscopy (TEM) as described in the J. Vac. Sci. Technol. B 10 (1992), p.  
491, by H. Cerva, Secondary-Ion Mass Spectroscopy (SIMS), Spreading  
Resistance (SR), and macroscopic Capacitance-Voltage (C-V) measurement,  
10 all described for example in S.M. Sze, "VLSI Technology", McGraw-Hill  
Book Co., New York, 1983 (in particular chapters 5 and 10). Other methods,  
currently under development are dopant density selective etching with a  
Scanning Tunneling Microscope (STM), which is known from L.P. Sadwick  
et al., J. Vac. Sci. Technol. B 10 (1992), p. 468, planar STM, described by  
15 H.E. Hessel et al. in J. Vac. Sci. Technol. B 9 (1991), p. 690, and  
cross-sectional STM, described by J.M. Halbout and M.B. Johnson in J.  
Vac. Sci. Technol. B 10 (1992), p. 508. Though being in some aspects  
useful, these techniques suffer from several drawbacks: they are either  
destructive or require a careful sample preparation, or have a limited lateral  
20 resolution or sensitivity to dopants.

25 One of the most recent methods to determine the dopant concentration is  
the Scanning Capacitance Microscope described in the United States patent  
US-A-5 065 103. It shows features of the scanning probe microscopy and of  
the conventional C-V technique. But even the Scanning Capacitance  
Microscope lacks a sufficient lateral resolution as will be required in the  
future. Further, it employs a lock-in technique to reduce the noise due to  
stray capacitance thus slowing down the scan process and makes a high  
throughput by this method improbable.

30

Another method, described in US-A-5 267 471, employs a cantilever with  
two different mechanical resonant frequencies. When using this device as a  
capacitance sensor, fractions of the resonant frequencies are applied to the

1      cantilever, and its movement is monitored by a laser interferometer and a  
2      subsequent lock-in amplifier. As above, the use of a lock-in amplifier  
3      severely restricts the bandwidth of the measurement.

5      The principles of scanning probe microscopies based on field-induced  
6      higher harmonic generations (SHM) are described for example by G.P.  
7      Kochanski in Phys. Rev. Lett. 62 (1989), No. 19, pp. 2285-2288, by W.  
8      Seifert et al. in Ultramicroscopy 42-44 (1992), pp. 379-387, by B. Michel et  
9      al. in Rev. Sci. Instrum. 63 (9), Sept. 1992, pp. 4080-4085, and by S.J.  
10     Stranick and P.S. Weiss in Rev. Sci. Instrum. 64 (5), May 1993, pp.  
11     1232-1234. In SHM techniques an electromagnetic field of Radio (rf) to  
12     optical frequencies, is applied to the tunneling gap of a conventional  
13     scanning tunnelling microscope (STM). Due to some electric properties of  
14     the tunneling gap, which are believed to be either non-linearities of the  
15     current-voltage curve or space-charge effects, higher frequencies  
16     (harmonics) are generated. Using these higher harmonics as feedback for  
17     the STM tip positioner, isolating films and semiconductors can be scanned.  
18     However, the feedback loop fails over a conducting surface, leading to a  
19     crash of the fragile tip on the surface. This fallacy prevents the large scale  
20     use of the SHM as an instrument for dopant profiling, as conducting areas  
21     are regularly encountered on an integrated circuit.

25     With regards to the described limitations of the art, it is therefore an object  
26     of the invention to provide an apparatus for determining the deflection of a  
27     cantilever which is particular suitable for cantilevers with small dimensions  
28     and hence very high resonance frequencies. A further object of the  
29     invention is a non-destructive method and apparatus to determine  
30     characteristic properties of a material, in particular the dopant profile, with a  
31     resolution expansible below 100 nm. The method and apparatus should be  
32     equally applicable to conductive and non-conductive surfaces. It is another  
33     object of the invention to increase the bandwidth of the deflection  
34     measurement with regard to the known devices.

1

## SUMMARY OF THE INVENTION

5 The above-mentioned and other objects and advantages are attained in accordance with the principles of the present invention as set forth in the appended claims.

10 Accordingly, in a basic variant the apparatus in accordance with the invention comprises a flexible cantilever, voltage biasing means to apply a DC voltage between the cantilever and either a sample to be investigated during operation of the apparatus or a "piggybacked" reference surface or tip, antenna means to receive radiation in the MHz and/or GHz range, and amplifying means designed to operate in this range. Due to non-linearities 15 of either the resistance-to-voltage or capacitance-to-voltage characteristic of the interface between the cantilever and the second surface, the radiation emitted from the interface area has not only one (fundamental) frequency, but simultaneously contains components with higher frequencies, the so-called harmonic signals. Though in principle all these components can 20 be used, it is found that in some embodiments of the invention advantageously harmonic signals, in particular the second and third harmonic signals, are exploited for measurements, as will be further described below. The preferred range of frequencies is 100 MHz to 100 GHz, whereby the lower limits is set by the efficiency of the higher harmonic 25 generation and the upper limits reflects the currently available equipment for the generation and detection of high frequency signals.

30 The generation of higher harmonics requires usually that the cantilever and the second surface, which can either be the surface of a sample or of a "piggybacked" plane or tip, form an interface consisting of a semi- or non-conductive boundary and a conductive boundary. However, it is found that the sensitivity of a device in accordance with the invention supports an embodiment in which both surfaces are made of semiconducting materials.

1 Thus, the device shows a high efficiency in the generation of higher  
harmonic signals, irrespective of the nature of the second boundary. As  
another advantage of the invention, a constant DC bias voltage can be  
chosen without the need of a re-adjustment when for example during a scan  
5 of the cantilever different surface materials are encountered.

10 The two boundaries are separated by preferably 0.1 nm to 100 nm. Using  
the voltage biasing means, a DC voltage can be applied to this interface.  
The oscillations of the cantilever then cause the emission of an electrical  
field signal oscillating with the resonance frequency and with higher  
harmonics, thereof, due to the non-linear capacitance-to-voltage  
15 characteristic of the interface. The emitted electrical field is detected by the  
antenna and the amplifier or the cascade of amplifiers and filters, preferably  
forming a spectrum analyzer. Variations of the force acting upon the tip of  
the cantilever, and hence the deflection of the cantilever can be detected as  
20 shifts in the frequency of the electrical field signal or in the amplitude of the  
cantilever's oscillation.

25 The basic variant of the invention can be augmented to a deflection  
detection and control apparatus by applying the output signal of the  
amplifier to feedback means which control positioning means, e.g.,  
piezoelectric fine positioning systems, known as such in the art, allowing in  
combination a control of the position of the cantilever with atomic precision.  
This embodiment of the invention especially suitable for cantilevers with a  
30 resonance frequency of several hundred MHz or higher. These cantilevers  
are too small to apply known optical methods, such as beam deflection or  
interferometry, as the light can no longer be properly focussed and the  
amount of light reflected by the cantilever falls below current detection  
thresholds.

30

As described with respect to the patent US-A-4 724 318, it is in principle  
known to use a "piggybacked" Scanning Tunneling Microscope (STM) to  
detect the deflection of a AFM cantilever. It will however become clear that

1 the differences with respect to this invention result in several advantages. Tunneling current detection requires the tip to approach the back of lever up to less than one nm. This close distance causes a strong damping and is impractical when measuring large forces and force gradients, i.e., large  
5 deflections. Another reason which prevented the use of this method in commercially available AFM microscopes is the lack of stability of the tunneling gap under ambient conditions. With an apparatus in accordance with the invention, the gap width can be enlarged up to 50 nm. The damping of the silicon cantilever is much smaller, while the sensitivity for  
10 measuring deflection can be maintained at a very high level. In addition, the new apparatus does not suffer from the stability problems characteristic for an AFM with tunneling current detection of the deflection. It even can be performed on surfaces that are covered with an insulating, e.g., oxide or nitride, layer

15

Embodiments of the invention can easily be applied to any type of existing cantilever without the need of an accurate adjustment or alteration of the cantilever itself. A device according to the invention is found to have a good signal-to-noise ratio and therefore does not require a lock-in amplifier,  
20 thereby increasing the bandwidth of the deflection measurement.

Obviously, the scope of the invention is not restricted to simple beam-shaped cantilevers with a single support. It can readily be applied to more complex designs of cantilevers, having for example two or more support points, a spiral-like shape, etc.  
25

Further embodiments of the invention concern the antenna which receives the electrical field emitted from the interface region: The antenna can either be a distinct conductive element or an integral part of the cantilever, of the  
30 sample carrier, or of the piggybacked element. In latter cases, means for separating the bias voltage and other low frequency components from the high frequency signal are provided, such as "bias tee" connectors. The antenna can also be integrated into a cavity, preferably into a tunable cavity,

1 as described for example by B. Michel et al. in Rev. Sci. Instrum. 63 (9),  
Sept. 1992, pp. 4080-4085. The use of a cavity allows the detection of a  
large percentage of the signal power provided that the cavity is tuned to the  
frequency of the signal. Without a cavity, a higher flexibility in measuring  
5 and instrument design is gained. The, however, reduced sensitivity may in  
this case be compensated by using specially designed high impedance  
filters and amplifiers.

10 A specific aspect of the invention is use of a device comprising a flexible  
cantilever and means for detecting higher harmonic electrical signals as  
described above for investigating heterogeneous surfaces, in particular for  
probing highly integrated circuits, i.e., dopant profiling.

15 It is known that the electrical signal emitted from the gap between tip and  
sample depends on the materials of which the boundaries of the interface  
are made of. However, the introduction of applicable dopant profilers failed  
so far as no known instrument has been versatile enough to cope with a  
complex surface as encountered in ICs. Though the scanning capacitance  
microscope is in principle able to scan across any surface, it has been  
20 impossible to maintain a high resolution under such arbitrary surface  
conditions. The invention solves this problem by using a device operable in  
an atomic force mode, in which the deflection of the cantilever is detected  
by any of the methods described above, and simultaneously enabling the  
detection of the electrical signal as emitted from the gap area.

25 Another embodiment further comprises means for generating an oscillating  
electrical field and coupling means to apply this field to the cantilever. In  
this embodiment, the frequency with which the gap between the tip of the  
cantilever and the surface of a sample is modulated is not determined by  
30 the resonance frequency of the cantilever but can be tuned to a  
predetermined value. This value may depend on the surface structure and  
composition of the sample to be investigated. Preferably a radio frequency  
or microwave frequency field is used. This embodiment is further improved

- 1 by providing appropriate filter means to separate the fundamental frequency signal, which is obscured by the externally supplied signal, from its higher harmonics.
- 5 In a variant of this embodiment, the externally supplied oscillating electrical field is utilized to control amplitude and oscillation frequency of the cantilever. This control is especially efficient when tuning the externally supplied field to the resonance frequency of the cantilever. Similar effect can be achieved when the cantilever oscillation is driven by a piezoelectric or piezoresistive elements forming part of the cantilever body with said elements being excited by externally provided electrical signals. Another alternative to excite oscillation is by providing a sufficient amount of thermal energy to the cantilever, which in this case should have a bimorph structure including material with different thermal expansion coefficients. The heat supply to the cantilever can be enhanced by including suitable heating elements into the cantilever structure.
- 10 sp In another embodiment of the invention, the tip is attached to means for measuring the current flowing through the gap between the tip and the surface. Thus, either the (DC) tunnel current as known from the conventional STM can be determined or an AC current arising from a small number of electrons which tunnel onto and from the surface to be studied under the influence of the applied AC electromagnetic field as described by Kochanski. In the latter case also applies to an insulator.
- 15
- 20
- 25 Both currents can be used as input signal to the feedback loop of the positioning device, giving the operator of an apparatus according to this invention two to four different methods of controlling the gap width between tip and sample.
- 30 In a particular preferred embodiment of the invention, the tip and the cantilever of the force sensor are combined to an atomic force cantilever with a conductive cladding or coating. This cladding can be applied to a normal AFM cantilever by any suitable deposition technique well known in

- 11 -

1 the art. This integrated tip structure reduces significantly the technical overhead as compared to a device in which a atomic force sensor has to be applied in parallel to the (metallic) tip of conventional scanning harmonic microscopes (SHMs).

5

It is immediately possible to apply the signal detection to an array of cantilevers, each tuned for example to a slightly different resonance frequency. The deflection of each cantilever can be accomplished by either coupling the input DC voltage or the input electromagnetic wave selectively 10 to each one of these cantilevers or by tuning a frequency detection device to its resonance frequency.

15 The efficiency of the apparatus can be further enhanced by employing an enclosing chamber and means for controlling the humidity in the interface region as described for example by J.-P. Bourgoin et al. (International Conference on Micro- and Nano-Engineering MNE '94, Davos, Switzerland, Sept. 26-29, 1994) In case of a known scanning surface harmonic microscope. The humidity when set to an appropriate value gives rise to 20 the formation of a tiny droplet in the interface region and thus concentrates the electrical field in this region.

25 These and other novel features believed characteristic of the invention are set forth in the appended claims. The invention itself however, as well a preferred mode of use, and further objects and advantages thereof, will best be understood by reference to the following detailed description of illustrative embodiments when read in conjunction with the accompanying drawings.

30

#### DESCRIPTION OF THE DRAWINGS

The invention is described in detail below with reference to the following drawings:

1 FIG. 1 shows a model of the tip-sample gap.

5 FIG. 2 shows a first embodiment of a deflection sensor in accordance  
with the invention.

10 FIG. 2B shows a device for ESR measurements including a second  
embodiment of the invention.

15 FIGs. 3 A, B show further variants of the deflection sensor according to the  
invention.

20 FIGs. 4 A, B, C illustrate the use of the invention as instrument for surface  
investigation with different embodiments.

25 FIGs. 5 A, B illustrate experimental results.

30 FIGs. 6 A, B, C illustrate further experimental results.

#### 20 MODE(S) FOR CARRYING OUT THE INVENTION

Referring now to FIG. 1, a RC parallel circuit 1 is shown as a model to facilitate the understanding of the generation of higher harmonics in the interface or gap separating a cantilever and a second surface. The RC parallel circuit 1 is an electrical model of this gap, to which a DC voltage is applied. The input microwave signal  $\omega$  as generated in a microwave generator (not shown) is coupled into the gap area, for example via either the tip or the sample holder. The input microwave signal has a frequency  $\omega$ . The radiation emerging from the gap includes components with harmonic frequencies  $n\omega$ . These components are generated due to non-linearity of the resistance  $R(V)$  and/or the capacitance  $C(V)$  with respect to the voltage.

1 Referring now to figure 2A, an example of the basic variant of the invention  
is shown schematically. A flexible cantilever 220 with a tip at its apex and  
the sample holder 230 with a sample 231 are connected to a DC voltage  
source 250, which provides an bias voltage across the interface. Due to the  
5 oscillations of the cantilever, which may either oscillate at its resonant  
frequency or at the frequency of an externally supplied signal, the gap  
between the tip and sample is modulated causing the emission of radiation  
including the fundamental  $\omega$  and higher harmonic frequencies  $n\omega$  signals.  
10 These signals are received by an antenna 261 and amplified in a microwave  
amplifier 260 for further processing (displaying, controlling, etc.). This  
simple variant of the invention is of particular interest when building large  
arrays of cantilevers. Every cantilever of an array may be tuned to a  
15 different base frequency. A spectrum analyzer is then employed to separate  
the contribution of each cantilever to the detected signal giving a ready  
possibility to observe the deflection of each cantilever in the array. The  
excitation energy necessary to balance the energy dissipation of the  
20 cantilever has to be provided in this basic variant externally, e.g. by  
heating, radiation, and the like. When no external field is supplied, it is  
desirable to have a high resonant frequency of the cantilever. Cantilevers  
which resonate at frequencies between 0.01 GHz and 1.0 GHz are known  
from Binh et al., Surface Science 301 (1994), L224.

Figure 2B depicts means for externally exciting the lever oscillation by  
electromagnetic radiation 240. A device for measuring the electron spin  
25 resonance (ESR) of a sample is shown, which differs from the one described  
by Rugar et al. in NATURE 360, 563 (1992), in that the deflection of the  
cantilever is sensed by the detection of higher harmonics generated in the  
gap between the cantilever 232 carrying the ESR sample and a second  
30 (reference or "piggybacked") plane provided with a metallic tip 222. The rf  
coil 240, the magnet 291, and the sweep coil 292 are standard parts of an  
ESR measurement equipment. The modulation of the magnetic field at the  
sample gives rise to a cantilever vibration amplitude of typically around one  
nanometer, detected as a variation of the higher harmonic signal. This

1 signal is generated in the gap between the tip 222 and the silicon cantilever  
232. The signal generator 293 sweeps the magnetic field to bring the spins  
in resonance with the applied rf frequency, which is half of the resonance  
frequency of the cantilever. A detection circuit 262 is tuned to higher  
5 harmonics of this resonance frequency.

Another variant of the invention is shown in FIG.3A. In this example, the  
microscope particularly includes a cantilever 320 made of semiconducting  
material 321 Facing its back plane is a metallic tip 323, which is connected  
10 to a microwave source 340. A DC voltage is applied to the tip 323 and the  
cantilever 320. The voltage can be tuned to a value appropriate for the  
material of the cantilever. Further clamping means (not shown) are provided  
to keep the distance between tip and cantilever at a default value of 50 to 100  
15 nm. It is important to notice that this gap width is well above the distance  
over which tunneling of electrons occurs, i.e. significantly larger than in  
case of the piggybacked STM described in the patent US-A-4 724 318. The  
gap width is also large enough to prevent a collision of the tip 323 and the  
cantilever 320 under normal conditions, hence, it is not necessary to  
20 provide the tip with a positioning system controlled by another feedback  
loop. To run however this variant of the invention in a mode which is  
commonly known in the field of scanning force microscopy as "constant  
force mode," an integrating circuit 371 is provided, which controls the  
positioning means 331 of the sample as part of a feedback loop 370.

25 In the described variant further an external microwave signal is fed through  
the tip 323 to the gap between the tip and the cantilever. The input  
microwave signal source 340 is connected to the DC voltage circuit by a  
bias tee 341. The emitted radiation  $\omega_{mw}$  is received by the antenna 361.  
The amplifying circuit includes a preamplifier 362, with a bandwidth ranging  
30 from 1GHz to 4GHz and an amplification of 40 dB, a band-pass filter 363  
(2.1-3.5 GHz) for eliminating noise and unsought frequency components  
from the signal. The following spectrum analyzer 364 produces a frequency

1 resolved display of the signal. The output of the spectrum analyzer can  
alternatively be used as input to the integrating circuit 371.

5 As another aspect of the invention, a unit comprising microwave source,  
antenna, amplifiers, and feedback circuit can be built attachable to any  
known atomic force microscope (AFM). The deflection of the AFM cantilever  
can be detected with an accuracy of approximately 10 picometer without  
encountering the stability problems which prevented the use of STM-based  
detection methods in commercial AFMs.

10 A compact design in accordance with the invention is shown in FIG. 3B,  
where the additional metallic tip is replaced by a metallic coating 322 of the  
cantilever 320. Further, the output of the spectrum analyzer 364 is connected  
15 to the input of a phase locked loop (PLL) 372 controller which forms part of  
two feedback loops 370, 350, the first of which is locked to the resonant  
frequency of the cantilever. This loop, which comprises a summer 374, is  
used to electrostatically excite the oscillation of the cantilever 320. As the  
PLL is responsive to frequency shifts in the signal, the shown device can be  
employed to measure the damping of the cantilevers oscillation. A constant  
20 damping mode can be achieved by connecting the rms (root mean square)  
output of the PLL after further smoothing by an integrator 373 as control  
signal to the positioning means 331 of the sample holder 330.

25 Referring now to FIGs. 4A, 4B, and 4C, variants of a surface inspection  
tool, e.g. a dopant profiling instrument, according to the invention are  
shown. The first variant, as depicted by FIG. 4A, an electrostatically excited  
version of the invention as described above (FIG. 3A), is provided with  
switching means 474. When the switch is in position 1, the detection of the  
30 higher harmonic is used for deflection control. In position 2 however the  
microwave source is connected to the gap between the cantilever 420 and  
the sample holder 430 making a dopant profiling possible. It is also possible  
to provide a second microwave source with a second base frequency. Using

1 this particular embodiment it is possible to simultaneously detect the  
deflection of the cantilever and inspect the surface of a sample.

With respect to the example described above, the dopant profiler of FIGs.  
5 4B and 4C comprises additional means to detect the deflection of the  
cantilever, said means being based on methods known in principle and  
partly described above. Examples are shown wherein the deflection of the  
cantilever is either measured by a piezoresistive method (FIG. 4B) or by a  
beam deflection apparatus measuring the intensity of a laser beam,  
10 reflected by the back of the cantilever (FIG. 4C). However, any other known  
deflection detection method can be applied instead.

In both embodiments the metal coating 422 of the cantilever 420 is  
connected to a current/voltage converter 490 to operate the cantilever in an  
15 STM mode. A switch 476 now is provided with the feedback circuit 470  
which allows to choose automatically between different input signals. The  
switch can be either programmed or controlled by an external device, if for  
example the topology of the sample is accurately known, which is the case  
in IC manufacturing. As an alternative, the deflection is monitored with at  
20 least a second deflection detection method, parallel to the one which  
currently supplies the input signal to the feedback circuit 470. In the latter  
case the switch 476 automatically alters its position when the currently  
applied signal deviates significantly from its expected values.

25 Both variants as shown in FIGs. 4B and 4C differ in the way, in which the  
radiation emanating from the gap area is received: The embodiment of FIG.  
4A includes a tunable cavity 465 as described for example by Michel et al.,  
allowing a preselection of the signal frequency and a very sensitive  
30 detection of the signal. very sensitive detection of radiation with a narrow  
bandwidth. In this embodiment the use of a deflection measurement method  
is preferred which does not interfere with the properties of the cavity as a  
resonator. Therefore, a piezoresistive layer 423 is incorporated into the  
cantilever body 420. The piezoresistive element is part of mainly a

1    Wheatstone bridge arrangement 480 to measure its resistance and therewith derive the deflection of the cantilever 420. The piezoresistive layer can be replaced by piezoelectric elements, which produce a voltage in sympathy with the bending of the cantilever.

5    In the embodiment of FIG. 4C, no cavity is used and the antenna is formed by the conductive coating 422 of the cantilever. Input and output paths of the high frequency signal are separated from the DC circuit 450 by bias-tee elements 441, 466. As said above, the absence of a cavity allows to use a broader variety of deflection measuring methods. In the shown embodiment 10 the intensity of a reflected laser beam 482 is measured, whereby this intensity depends on the bending of the cantilever 420.

15    It is seen as an obvious task for a skilled person to combine different elements of the aforescribed embodiments, in particular to select a specific way of coupling the input signal to the gap and coupling the output signal to the amplifier cascade, to replace the conductive coating of the cantilever by a cantilever made of conductive base material, or to replace the coating by a piggybacked tip as shown in FIG. 3A.

20    As said above, the new microscope in accordance with the invention is advantageously used to characterize the surface of integrated circuits (IC). Figures 5 shows results obtained by investigating an n-type silicon sample doped with boron ions. Figure 5A depicts the sample structure consisting of 25 alternating stripes of an and p+ doped silicon. Each stripe has a width of approximately ten  $\mu\text{m}$ . Such a grating can be found in a similar form as source/channel/drain area of the PMOS device. In FIG. 5B the intensity of the second harmonic signal is shown as a function of the bias voltage and the position of the tip along a line running perpendicularly to the n and p+ doped stripes. The line-scans are taken at -1.45 V (a) , -0.55 V (b) , and 1.2 V (c), respectively. For reasons of clarity, the origins of the curves are shifted and curve b is enlarged by a factor of 5. Using these scans regions 30 having a high concentration of dopants can be distinguished from regions

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1 with a low concentration, or from depletion zones. Figures 6 shows similar  
results gained by investigating a sample doped with arsenic (n+). The  
lines-scans, taken with a bias voltage of 1.15 V (a), -1.15 V (b), and -1.50 V  
(c), respectively, clearly show the lateral dopant profile. The peak amplitude  
5 is much larger in the low-doped regions than it is in the high-doped regions.  
The resolution found lies below 35 nm. The resolution can be enhanced by  
controlling the humidity within the microscope. A simultaneously recorded  
line-scan (d) shows the physical height of the sample as measured in the  
STM and AFM operation mode of the microscope. The measurement is also  
10 depicted in a three-dimensional plot (FIG. 6C) with the horizontal axes being  
the bias voltage in volts and the position in nanometer, respectively. The  
vertical axis gives the second harmonic signal in nanoVolts (nV).

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## CLAIMS

1. An apparatus for measuring a force exerted upon or a deflection of a flexible cantilever (220, 320, 420), especially of an Atomic Force Microscopy (AFM) cantilever, comprising antenna means (261, 263, 361, 461), amplifying means (260, 262, 362-364, 462-464), and means (250, 350, 450) to apply in operation a DC voltage to said cantilever.
2. The apparatus in accordance with claim 1, wherein the amplifying means (260, 262, 362-364, 462-464) are designed to detect a higher harmonic ( $n\omega$ ) of a high frequency signal ( $\omega$ ).
3. The apparatus in accordance with claim 1, wherein the amplifying means (260, 262, 362-364, 462-464) are designed to operate in a frequency range of 10 MHz to 100 GHz.
4. The apparatus in accordance with claim 1, wherein either the cantilever (220, 320, 420), sample holding means (230, 330, 430), or a reference plane or tip (323, 423) form a part of the antenna means.
5. The apparatus in accordance with claim 1, further comprising means (240, 340, 341, 440, 441) for exciting oscillations of the cantilever (320, 420).
6. The apparatus in accordance with claim 1, further comprising means (240, 340, 341, 440, 441) for applying a high frequency electrical signal to the gap between the cantilever and a sample, or to the gap between the cantilever and a reference plane or tip (323, 423).
7. The apparatus in accordance with claim 1, further comprising a cavity (465) with conductive walls enclosing the cantilever (420), preferably with one of said walls being moveable relatively to the others.

- 1 8. The apparatus in accordance with claim 1, wherein the cantilever  
comprises electrically conductive material (322, 422).
- 5 9. The apparatus in accordance with claim 1, preferably to be used as  
dopant profiler, further comprising magnetic or piezoelectric actuator  
means for controlling the distance between cantilever (320) and the  
surface of a sample (331), force detection means (480, 482) for  
measuring the deflection of the cantilever, and switchable feedback  
means (470, 475, 476) for controlling said actuator means, said  
10 feedback means being switchable to said force detection or to the  
output of the amplifying means.
- 15 10. The apparatus in accordance with claim 1, preferably to be used as  
dopant profiler, further comprising magnetic or piezoelectric actuator  
means for controlling the distance between cantilever (320) and the  
surface of a sample (331), means (490) for detecting a tunnel current  
between tip and sample, force detection means (480, 482) for  
measuring the deflection of the cantilever, and switchable feedback  
means (470, 475, 476) for controlling said actuator means, said  
20 feedback means being switchable to said tunnel current, to said force  
detection, or to the output of the amplifying means.
- 25 11. Sample analyzing apparatus, comprising an apparatus in accordance  
with claim 1, means for positioning a sample (330) means for processing  
measured force or deflection signals to generate a screen display, and  
means for permanently storing the processed force or deflection signals  
on a magnetic medium.
- 30 12. A method for measuring a force exerted upon or a deflection of a  
flexible cantilever (220, 320, 420), especially of an Atomic Force  
Microscopy (AFM) cantilever, comprising steps of generating a high  
frequency radiation in a gap between said cantilever and a second

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1       surface (230, 231, 323, 330, 423), receiving and amplifying said radiation  
and determining frequency shifts and/or amplitude shifts thereof.

5       13. The method in accordance with claim 12, wherein oscillations of the  
flexible cantilever (220, 320, 420) are excited by an externally applied  
force.

10      14. The method in accordance with claim 13, wherein oscillations of the  
flexible cantilever (220, 320, 420) are excited by an externally applied  
electrical signal.

15      15. The method in accordance with claim 12, applied for investigating  
surface and/or volume properties of a sample (231, 331).

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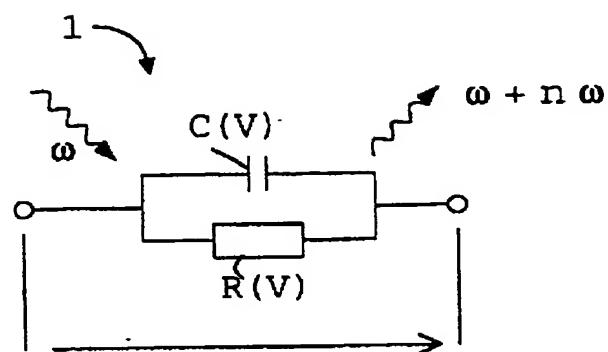
 $V_{dc}$ 

Fig.1

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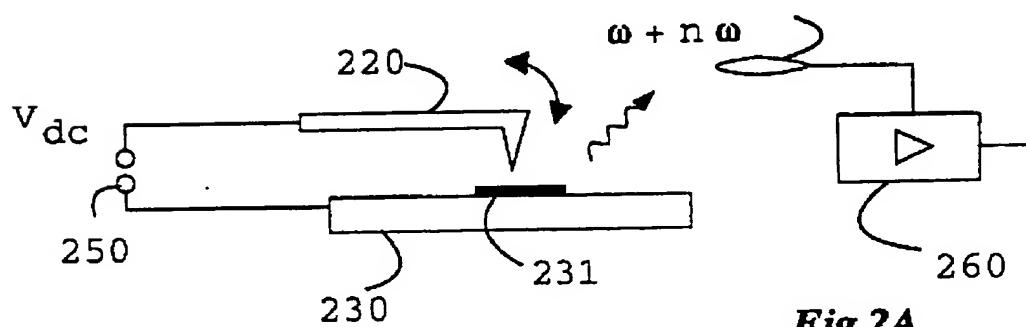


Fig.2A

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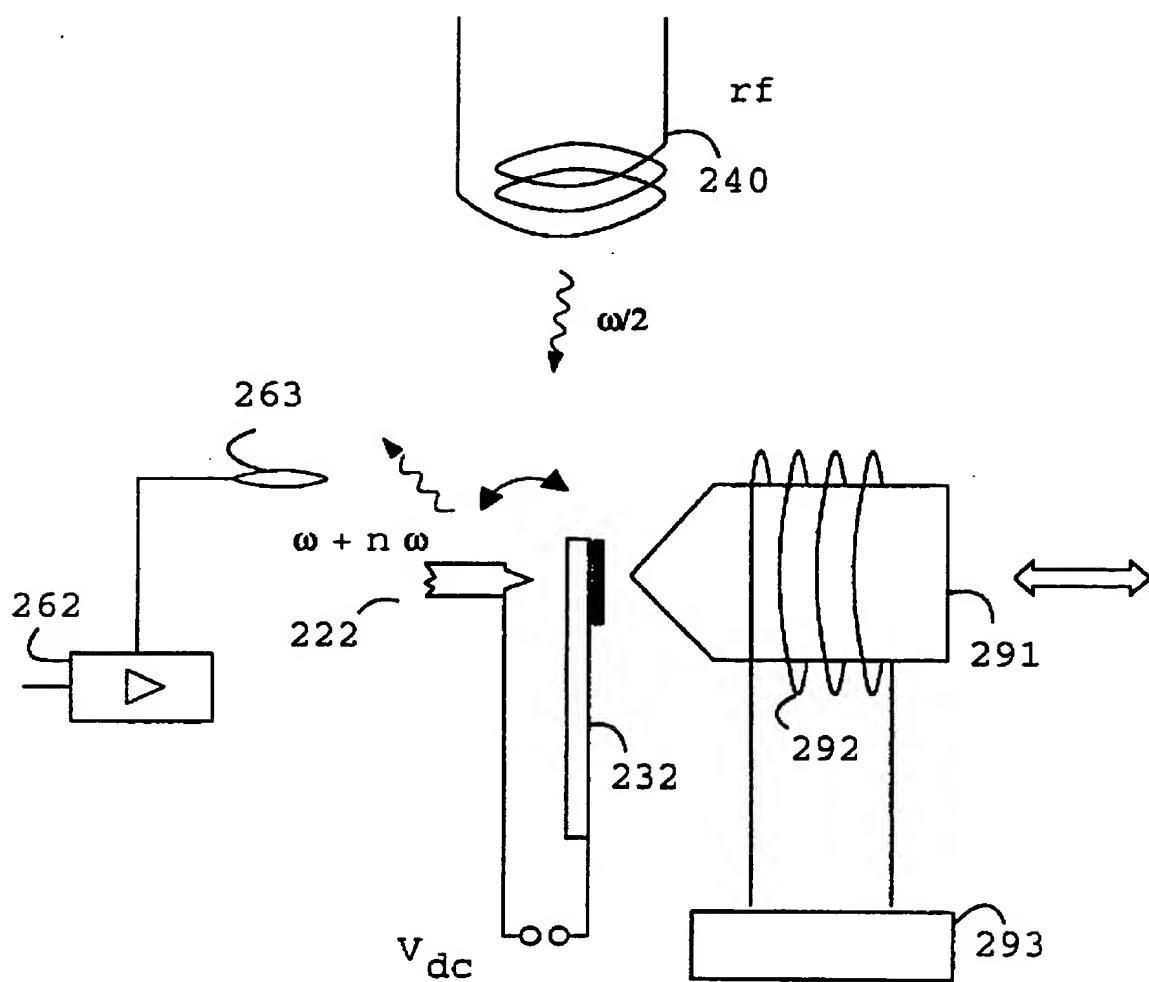


Fig.2B

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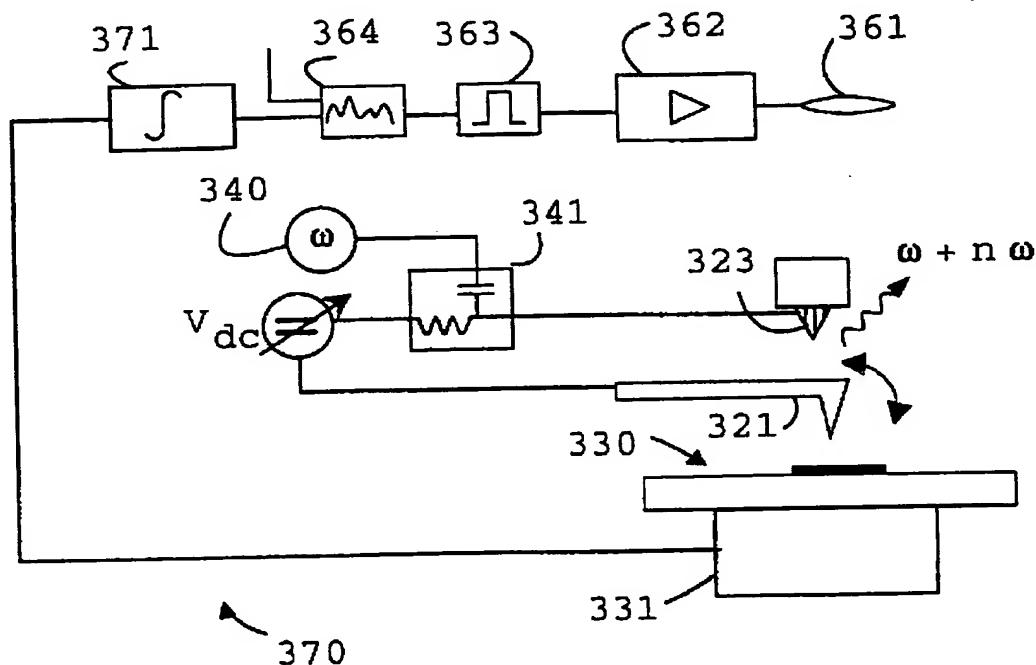


Fig.3A

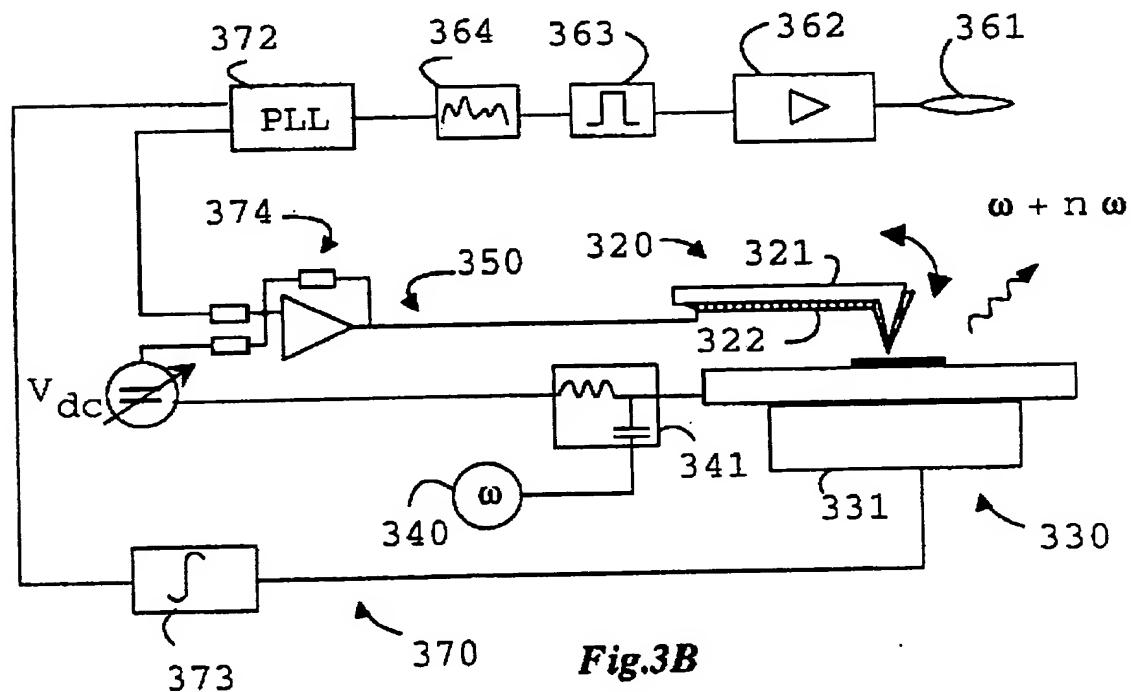


Fig.3B

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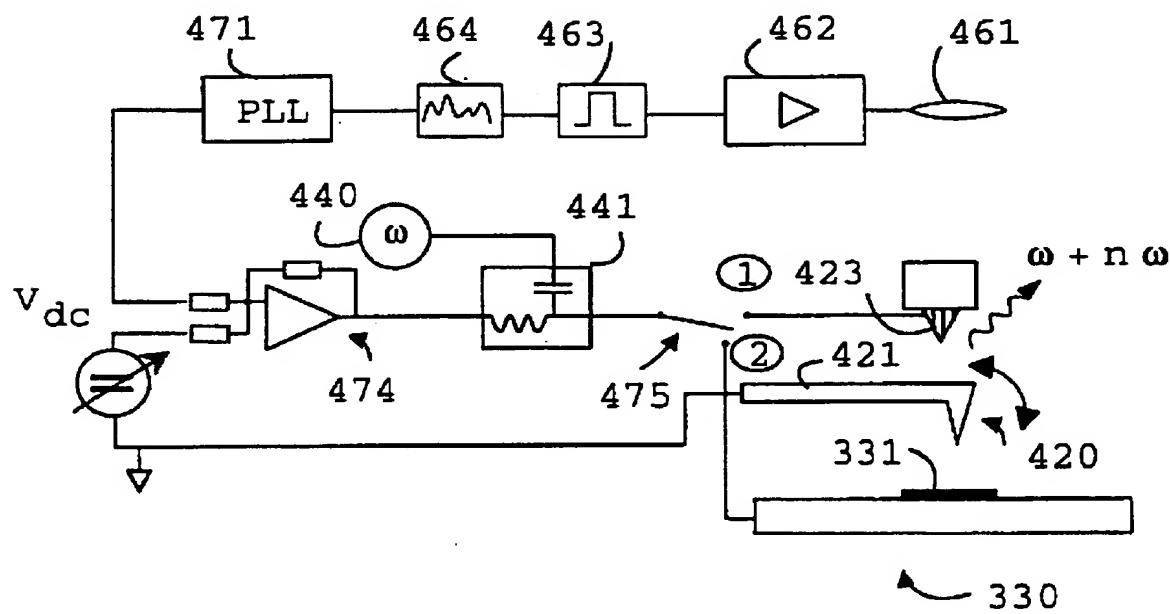


Fig.4A

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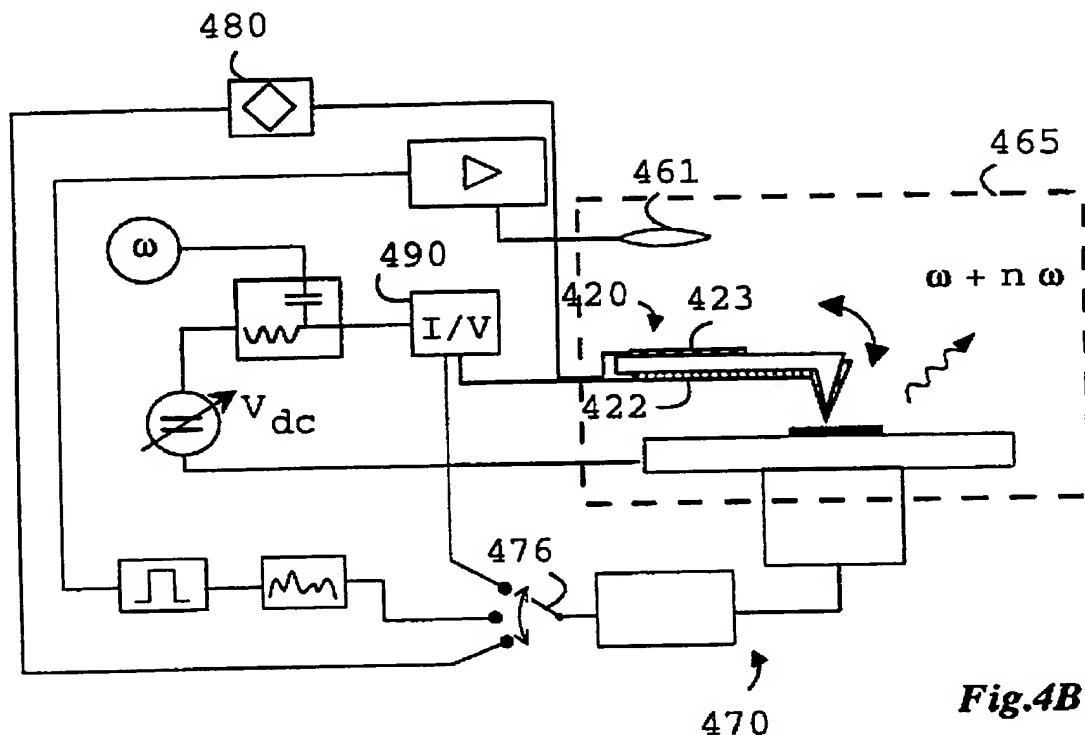


Fig. 4B

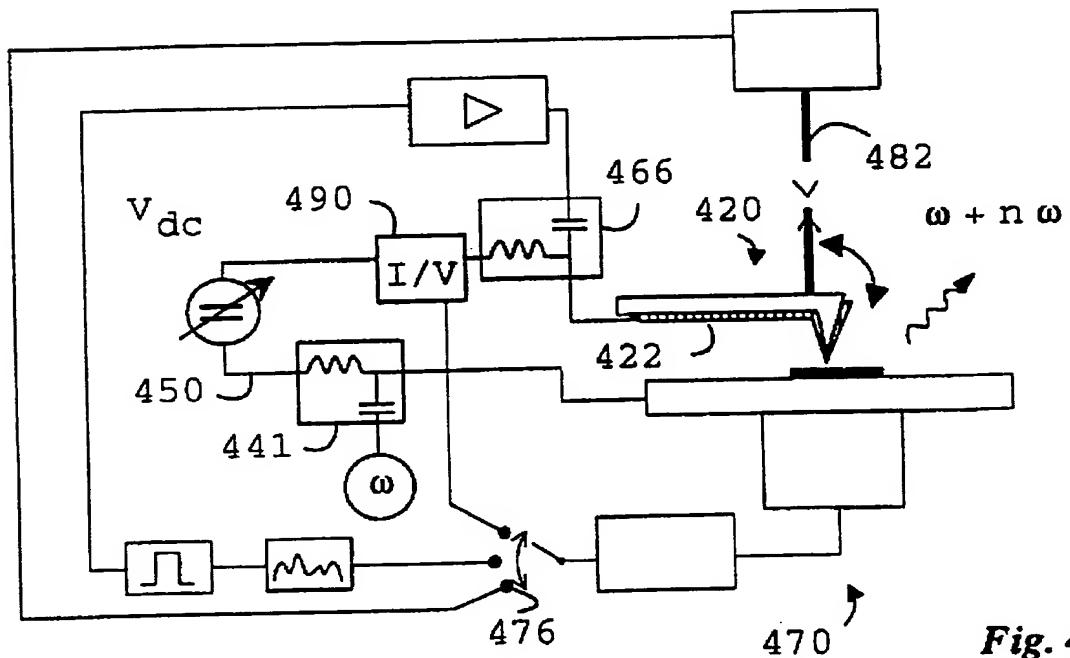
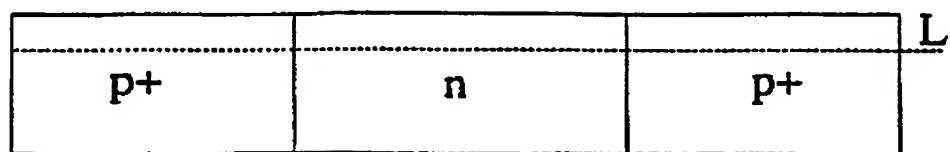
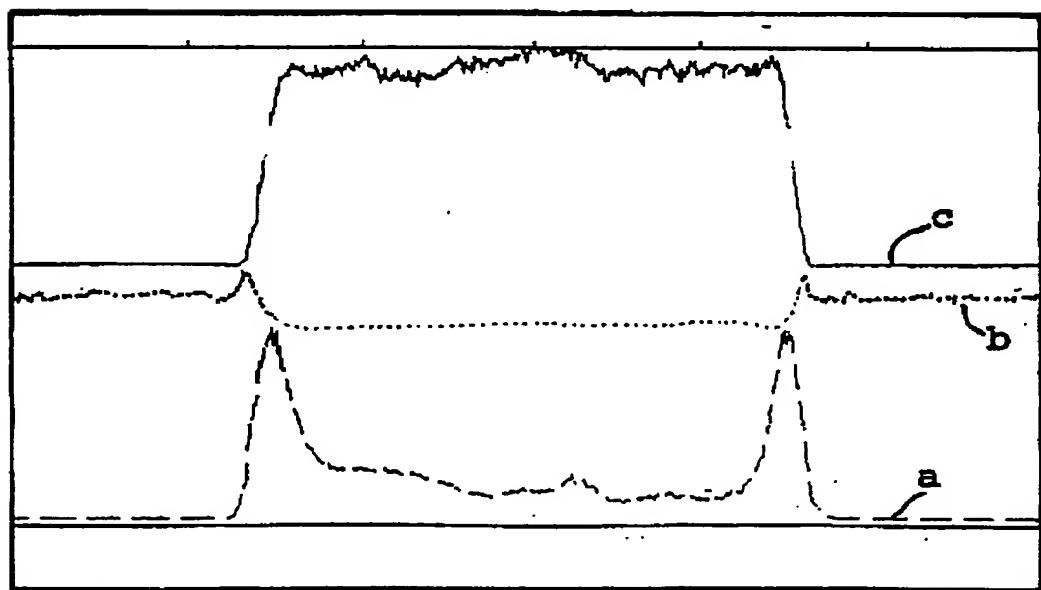


Fig. 4C

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*Fig.5A*



*Fig.5B*

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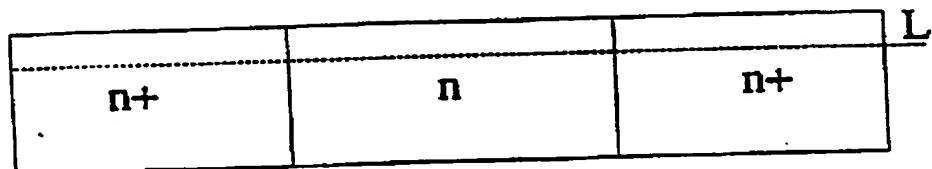


Fig.6A

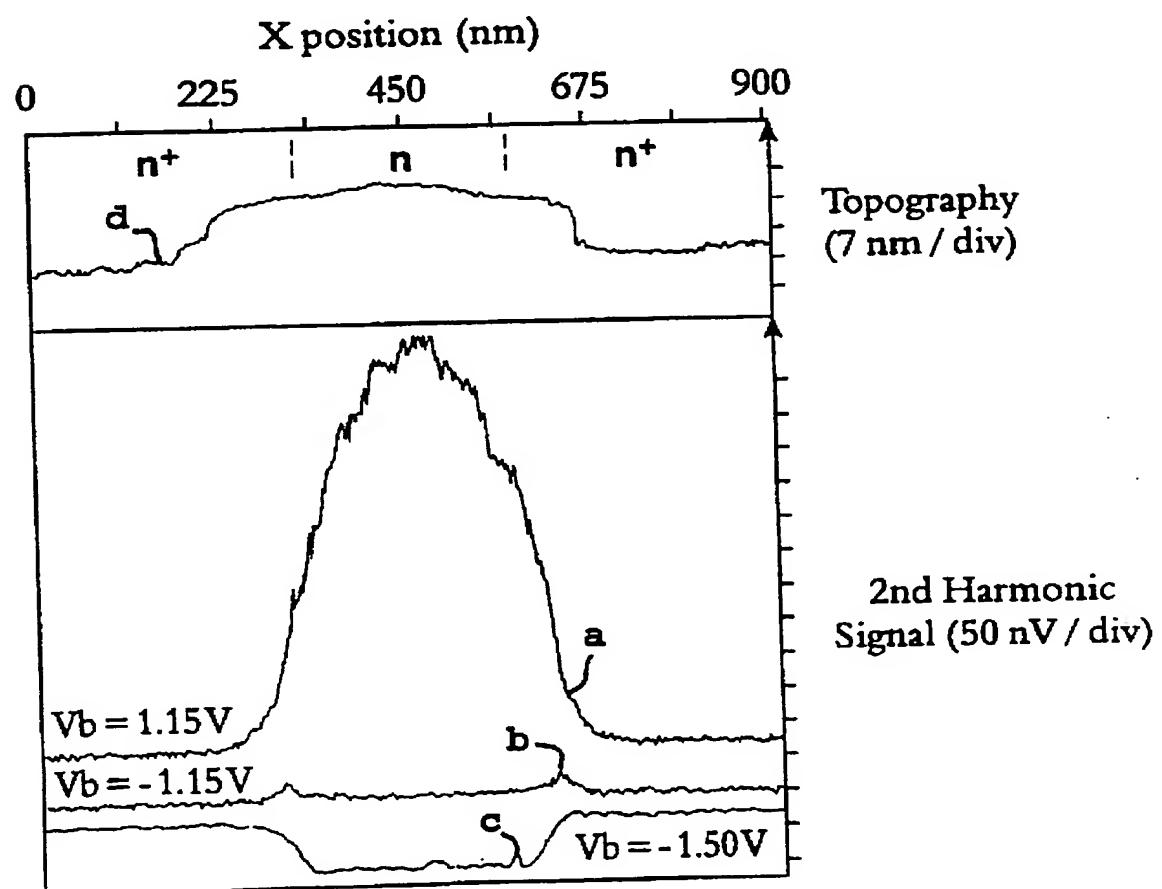
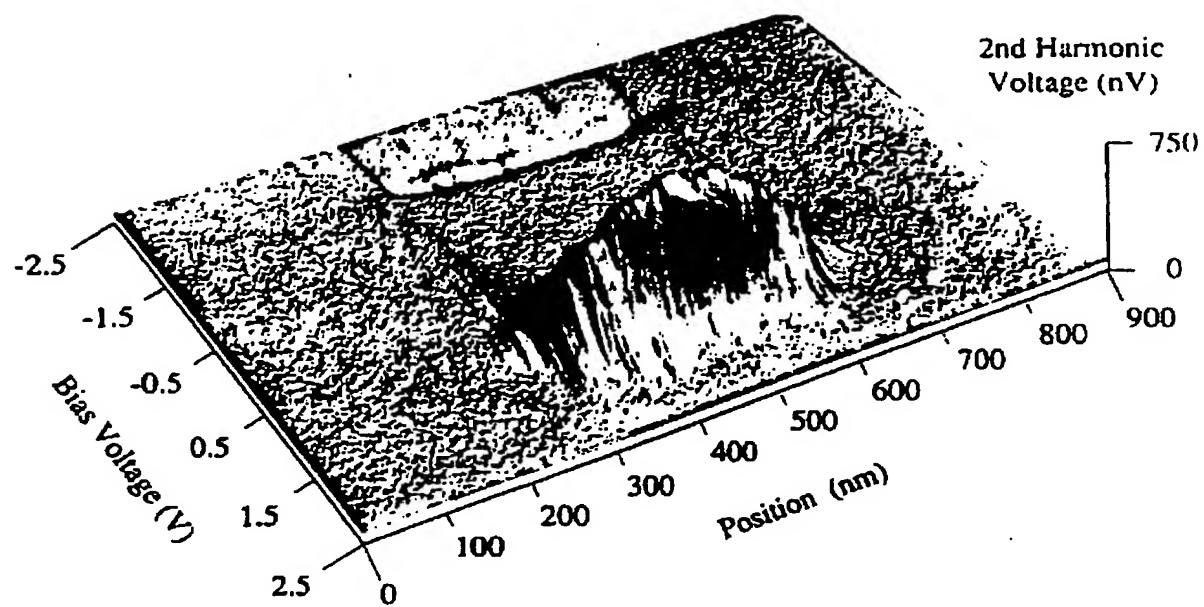


Fig.6B



**Fig.6C**

# INTERNATIONAL SEARCH REPORT

International Application No  
PCT/EP 95/00431

**A. CLASSIFICATION OF SUBJECT MATTER**  
IPC 6 G01B7/34

According to International Patent Classification (IPC) or to both national classification and IPC

**B. FIELDS SEARCHED**

Minimum documentation searched (classification system followed by classification symbols)

IPC 6 G01B

Documentation searched other than minimum documentation to the extent that such documents are included in the fields searched

Electronic data base consulted during the international search (name of data base and, where practical, search terms used)

**C. DOCUMENTS CONSIDERED TO BE RELEVANT**

Category	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
Y	<p>ELECTRONICS LETTERS, 3 DEC. 1992, UK, vol. 28, no. 25, ISSN 0013-5194, pages 2302-2303, HOU A S ET AL 'Picosecond electrical sampling using a scanning force microscope' see the whole document</p> <p>---</p> <p>PHYSICAL REVIEW B (CONDENSED MATTER), 15 MAY 1990, USA, vol. 41, no. 14, ISSN 0163-1829, pages 10229-10232, KRIEGER W ET AL 'Generation of microwave radiation in the tunneling junction of a scanning tunneling microscope' see the whole document</p> <p>---</p> <p>---</p>	1-6,8, 11-15
Y		1-6,8, 11-15

Further documents are listed in the continuation of box C.

Patent family members are listed in annex.

Special categories of cited documents :

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- "&" document member of the same patent family

1

Date of the actual completion of the international search	Date of mailing of the international search report
6 November 1995	20.11.95
Name and mailing address of the ISA European Patent Office, P.B. 5818 Patentstaan 2 NL - 2280 HV Rijswijk Tel. (+ 31-70) 340-2040, Tx. 31 651 epo nl Fax (+ 31-70) 340-3016	Authorized officer  Brock, T

## INTERNATIONAL SEARCH REPORT

International Application No  
PCT/EP 95/00431

## C(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

Category	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
E	EP,A,0 648 999 (HITACHI LTD) 19 April 1995 see column 3, line 20 - column 5, line 33; figure 1 see column 8, line 5 - column 9, line 58; figure 6 ---	1,3-7, 11-15
A	APPLIED PHYSICS LETTERS, 17 OCT. 1994, USA, vol. 65, no. 16, ISSN 0003-6951, pages 2045-2047, BOURGOIN J -P ET AL 'Semiconductor characterization with the scanning surface harmonic microscope'	1-4,6, 9-12,15
A	MICRO- AND NANOENGINEERING 94. INTERNATIONAL CONFERENCE ON MICRO- AND NANOFABRICATION, DAVOS, SWITZERLAND, 26-29 SEPT. 1994, vol. 27, no. 1-4, ISSN 0167-9317, MICROELECTRONIC ENGINEERING, FEB. 1995, NETHERLANDS, pages 539-542, JOHNSON M B ET AL 'Doping profiling with scanning surface harmonic microscopy' cited in the application ---	1-4,6, 9-12,15
A	IBM TECHNICAL DISCLOSURE BULLETIN, vol. 36, no. 10, 10 October 1993 NEW YORK US, pages 571-572, 'Improved method for dopant profiling by force microscopy' see the whole document ---	1,9,10, 15
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A	10 YEARS OF STM. 6TH INTERNATIONAL CONFERENCE ON SCANNING TUNNELING MICROSCOPY, INTERLAKEN, SWITZERLAND, 12-16 AUG. 1991, vol. 42-44, pt.A, ISSN 0304-3991, ULTRAMICROSCOPY, JULY 1992, NETHERLANDS, pages 379-387, SEIFERT W ET AL 'Scanning tunneling microscopy at microwave frequencies' cited in the application ---	1-4,6,7, 11,12,15

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International Application No  
PCT/EP 95/00431

## C.(Continuation) DOCUMENTS CONSIDERED TO BE RELEVANT

Category *	Citation of document, with indication, where appropriate, of the relevant passages	Relevant to claim No.
A	REVIEW OF SCIENTIFIC INSTRUMENTS, APRIL 1994, USA, vol. 65, no. 4, pt.1, ISSN 0034-6748, pages 918-921, STRANICK S J ET AL 'A tunable microwave frequency alternating current scanning tunneling microscope' ---	1,2,4,6, 11,12,15
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**INTERNATIONAL SEARCH REPORT**

Information on patent family members

Int'l Application No

**PCT/EP 95/00431**

Patent document cited in search report	Publication date		Patent family member(s)	Publication date
EP-A-0648999	19-04-95	JP-A-	7167868	04-07-95
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